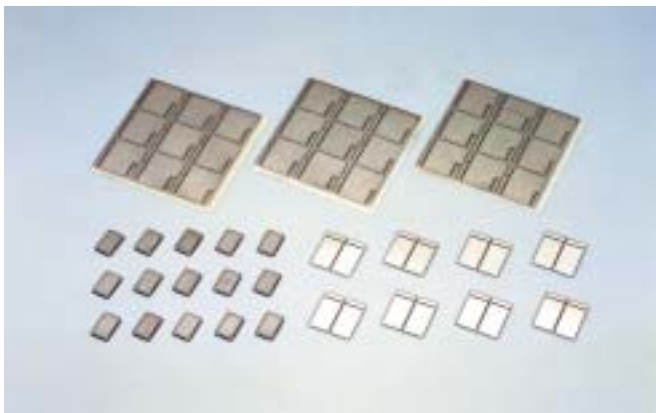


■ Aluminum Nitride Metallized Substrates

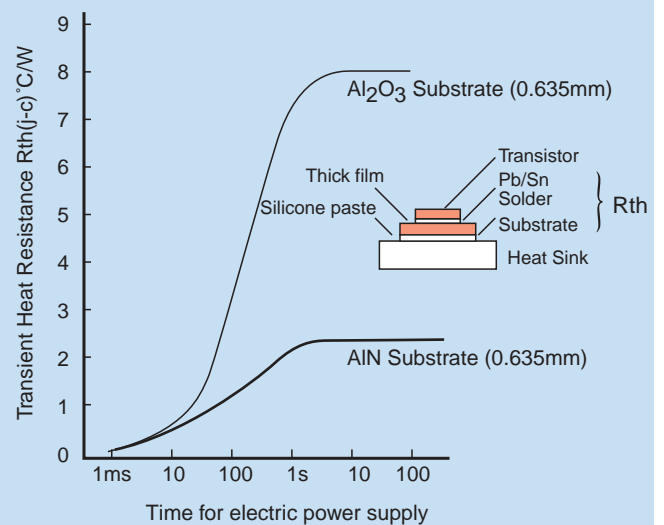
Molybdenum or tungsten pastes can be fired (co-fired and/or post-fired) onto the surfaces of aluminum nitride substrates, yielding highly reliable metallized substrates. Metallized surfaces can be plated with nickel and gold, and they also excel in soldering and wire bonding.

■ Standard specification of metallized aluminum nitride substrates

	Specification
Metallized strength	$\geq 3\text{Kg/mm}^2$
Heat up test	450°C(in N ₂) X 10 min. heat up, no color change, no blister on the metallized surface
Heat cycle test	-50~+150, 1000 cycle satisfied (MIL-STD-883D -1010-2 TEST (C))



Transient Heat Resistance (TAN-070)



■ Other Aluminum Nitride Substrates

Multilayer co-fire metallized substrates, thin-film metallized substrates and mirror finished plain substrates or Aluminum Nitride packages can be supplied.

■ Design rule for multilayer substrate

Item	Standard
Width of circuitry pattern	125 μm
Interval space of pattern	125
Diameter of land	250
Diameter of via	120
Interval space of land / pattern	250
Pitch of via	350